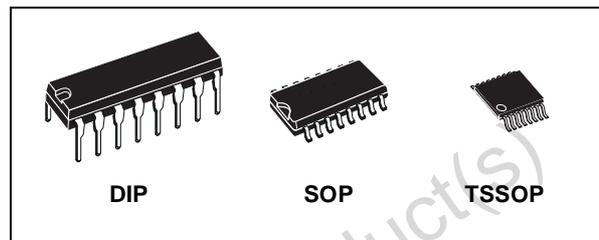




# M74HCT367

## HEX BUS BUFFER WITH 3 STATE OUTPUT NON INVERTING

- HIGH SPEED:  
 $t_{PD} = 14\text{ns}$  (TYP.) at  $V_{CC} = 4.5\text{V}$
- LOW POWER DISSIPATION:  
 $I_{CC} = 4\mu\text{A}$ (MAX.) at  $T_A=25^\circ\text{C}$
- COMPATIBLE WITH TTL OUTPUTS :  
 $V_{IH} = 2\text{V}$  (MIN.)  $V_{IL} = 0.8\text{V}$  (MAX)
- SYMMETRICAL OUTPUT IMPEDANCE:  
 $|I_{OH}| = I_{OL} = 6\text{mA}$  (MIN)
- BALANCED PROPAGATION DELAYS:  
 $t_{PLH} \cong t_{PHL}$
- PIN AND FUNCTION COMPATIBLE WITH  
 74 SERIES 367



### ORDER CODES

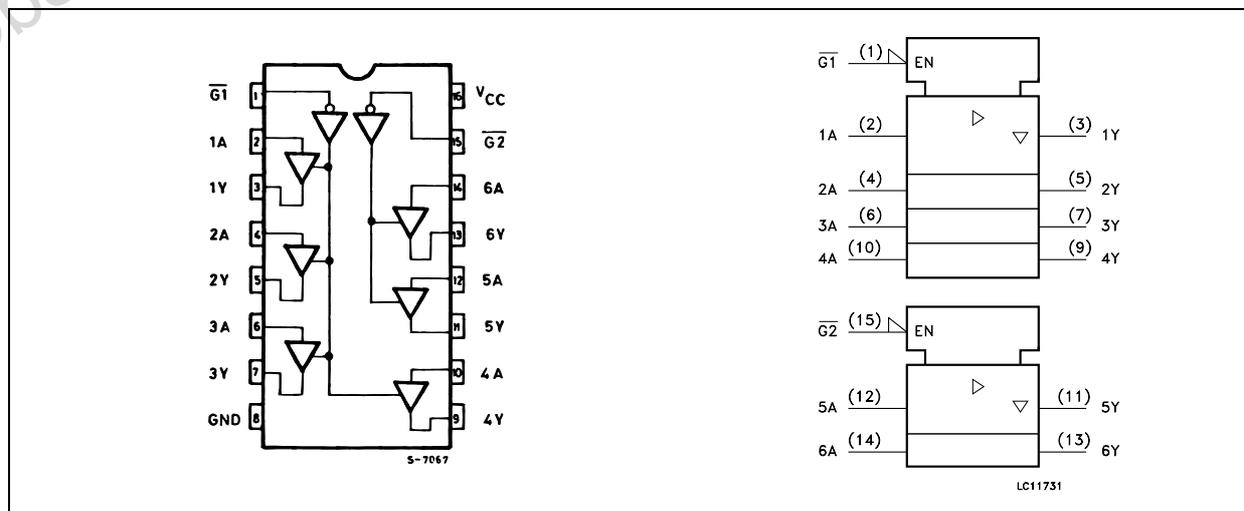
PACKAGE	TUBE	T & R
DIP	M74HCT367B1R	
SOP	M74HCT367M1R	M74HCT367RM13TR
TSSOP		M74HCT367TTR

### DESCRIPTION

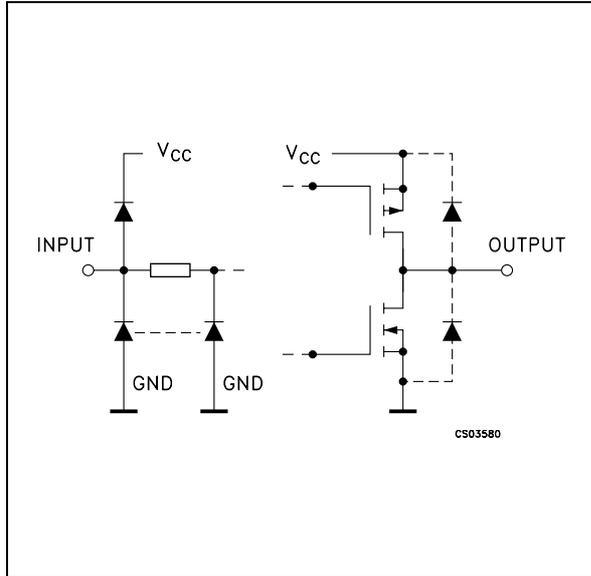
The M74HCT367 is an high speed CMOS HEX BUS BUFFER 3-STATE OUTPUTS fabricated with silicon gate C<sup>2</sup>MOS technology. This device contains six buffers, four buffers are controlled by an enable input ( $\overline{G1}$ ) and the other two buffers are controlled by the other enable input ( $\overline{G2}$ ); the outputs of each buffer group are enabled when  $\overline{G1}$  and/or  $\overline{G2}$  inputs are held low,

and when held high, these outputs are disabled in a high-impedance state. All inputs are equipped with protection circuits against static discharge and transient excess voltage.

### PIN CONNECTION AND IEC LOGIC SYMBOLS



**INPUT AND OUTPUT EQUIVALENT CIRCUIT**



**PIN DESCRIPTION**

PIN No	SYMBOL	NAME AND FUNCTION
1, 15	$\overline{G1}, \overline{G2}$	3 State Output Enable Input
2, 4, 6, 10, 12, 14	1A to 6A	Data Inputs
3, 5, 7, 9, 11, 13	1Y to 6Y	Data Outputs
8	GND	Ground (0V)
16	V <sub>CC</sub>	Positive Supply Voltage

**TRUTH TABLE**

INPUTS		OUTPUTS
$\overline{G}$	A <sub>n</sub>	Y <sub>n</sub>
L	L	L
L	H	H
H	X	Z

X: Don't Care  
Z: High Impedance

**ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	Supply Voltage	-0.5 to +7	V
V <sub>I</sub>	DC Input Voltage	-0.5 to V <sub>CC</sub> + 0.5	V
V <sub>O</sub>	DC Output Voltage	-0.5 to V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	DC Input Diode Current	± 20	mA
I <sub>OK</sub>	DC Output Diode Current	± 20	mA
I <sub>O</sub>	DC Output Current	± 35	mA
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground Current	± 70	mA
P <sub>D</sub>	Power Dissipation	500(*)	mW
T <sub>stg</sub>	Storage Temperature	-65 to +150	°C
T <sub>L</sub>	Lead Temperature (10 sec)	300	°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied

(\*) 500mW at 65 °C; derate to 300mW by 10mW/°C from 65°C to 85°C

**RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	Supply Voltage	4.5 to 5.5	V
V <sub>I</sub>	Input Voltage	0 to V <sub>CC</sub>	V
V <sub>O</sub>	Output Voltage	0 to V <sub>CC</sub>	V
T <sub>op</sub>	Operating Temperature	-55 to 125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (V <sub>CC</sub> = 4.5 to 5.5V)	0 to 500	ns

## DC SPECIFICATIONS

Symbol	Parameter	Test Condition		Value						Unit	
		V <sub>CC</sub> (V)		T <sub>A</sub> = 25°C			-40 to 85°C		-55 to 125°C		
				Min.	Typ.	Max.	Min.	Max.	Min.		Max.
V <sub>IH</sub>	High Level Input Voltage	4.5 to 5.5		2.0			2.0		2.0		V
V <sub>IL</sub>	Low Level Input Voltage	4.5 to 5.5				0.8		0.8		0.8	V
V <sub>OH</sub>	High Level Output Voltage	4.5	I <sub>O</sub> = -20 μA	4.4	4.5		4.4		4.4		V
			I <sub>O</sub> = -6.0 mA	4.18	4.31		4.13		4.10		
V <sub>OL</sub>	Low Level Output Voltage	4.5	I <sub>O</sub> = 20 μA		0.0	0.1		0.1		0.1	V
			I <sub>O</sub> = 6.0 mA		0.17	0.26		0.33		0.40	
I <sub>I</sub>	Input Leakage Current	5.5	V <sub>I</sub> = V <sub>CC</sub> or GND			± 0.1		± 1		± 1	μA
I <sub>OZ</sub>	High Impedance Output Leakage Current	5.5	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> V <sub>O</sub> = V <sub>CC</sub> or GND			± 0.5		± 5		± 10	μA
I <sub>CC</sub>	Quiescent Supply Current	5.5	V <sub>I</sub> = V <sub>CC</sub> or GND			4		40		80	μA
Δ I <sub>CC</sub>	Additional Worst Case Supply Current	5.5	Per Input pin V <sub>I</sub> = 0.5V or V <sub>I</sub> = 2.4V Other Inputs at V <sub>CC</sub> or GND I <sub>O</sub> = 0			2.0		2.9		3.0	mA

AC ELECTRICAL CHARACTERISTICS (C<sub>L</sub> = 50 pF, Input t<sub>r</sub> = t<sub>f</sub> = 6ns)

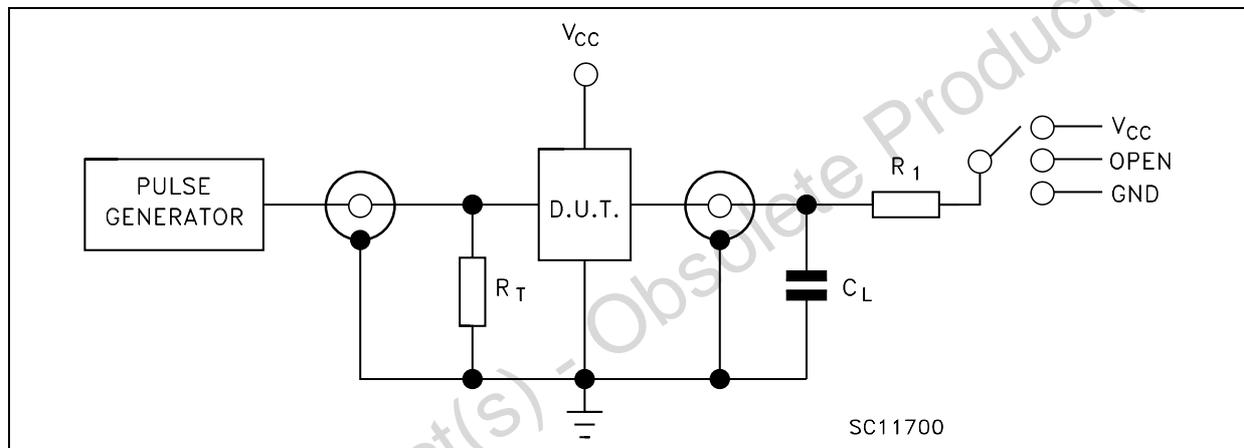
Symbol	Parameter	Test Condition		Value						Unit		
		V <sub>CC</sub> (V)	C <sub>L</sub> (pF)	T <sub>A</sub> = 25°C			-40 to 85°C		-55 to 125°C			
				Min.	Typ.	Max.	Min.	Max.	Min.		Max.	
t <sub>TLH</sub> t <sub>THL</sub>	Output Transition Time	4.5	50		7	12		15		18	ns	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay Time	4.5	50		14	22		28		33	ns	
		4.5	150		18	28		35		42		
t <sub>PZL</sub> t <sub>PZH</sub>	High Impedance Output Enable Time	4.5	50	R <sub>L</sub> = 1 KΩ		16	25		31		38	ns
		4.5	150	R <sub>L</sub> = 1 KΩ		20	31		39		47	
t <sub>PLZ</sub> t <sub>PHZ</sub>	High Impedance Output Disable Time	4.5	50	R <sub>L</sub> = 1 KΩ		18	25		31		38	ns

**CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Test Condition		Value						Unit	
		V <sub>CC</sub> (V)		T <sub>A</sub> = 25°C			-40 to 85°C		-55 to 125°C		
				Min.	Typ.	Max.	Min.	Max.	Min.		Max.
C <sub>IN</sub>	Input Capacitance				5	10		10		10	pF
C <sub>PD</sub>	Power Dissipation Capacitance (note 1)				47						pF

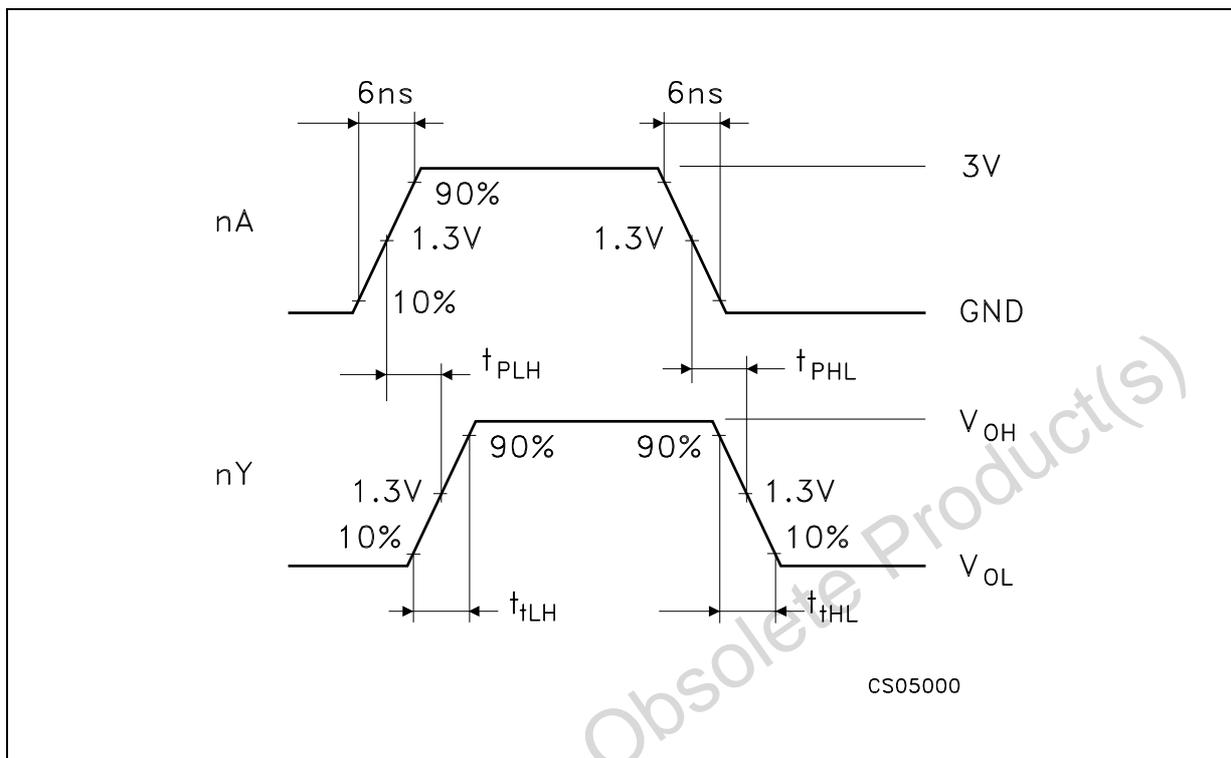
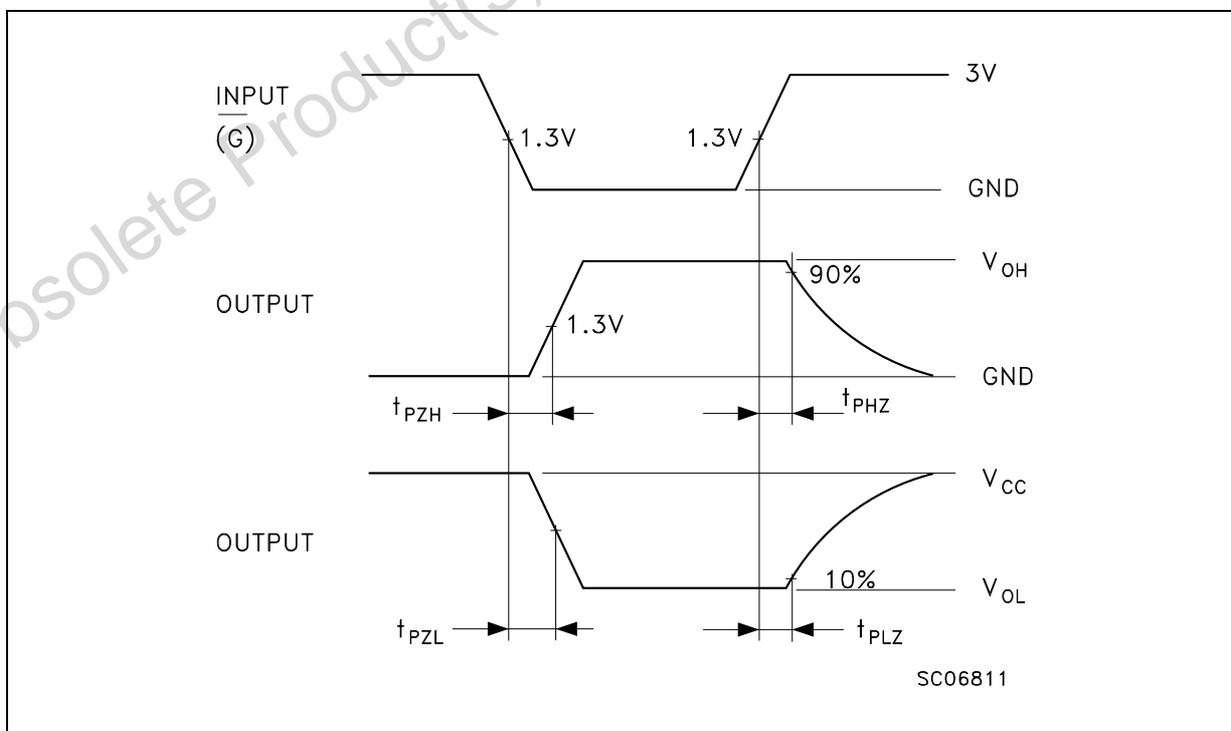
1) C<sub>PD</sub> is defined as the value of the IC's internal equivalent capacitance which is calculated from the operating current consumption without load. (Refer to Test Circuit). Average operating current can be obtained by the following equation. I<sub>CC(oper)</sub> = C<sub>PD</sub> × V<sub>CC</sub> × f<sub>IN</sub> + I<sub>CC</sub>/6 (per Channel)

**TEST CIRCUIT**



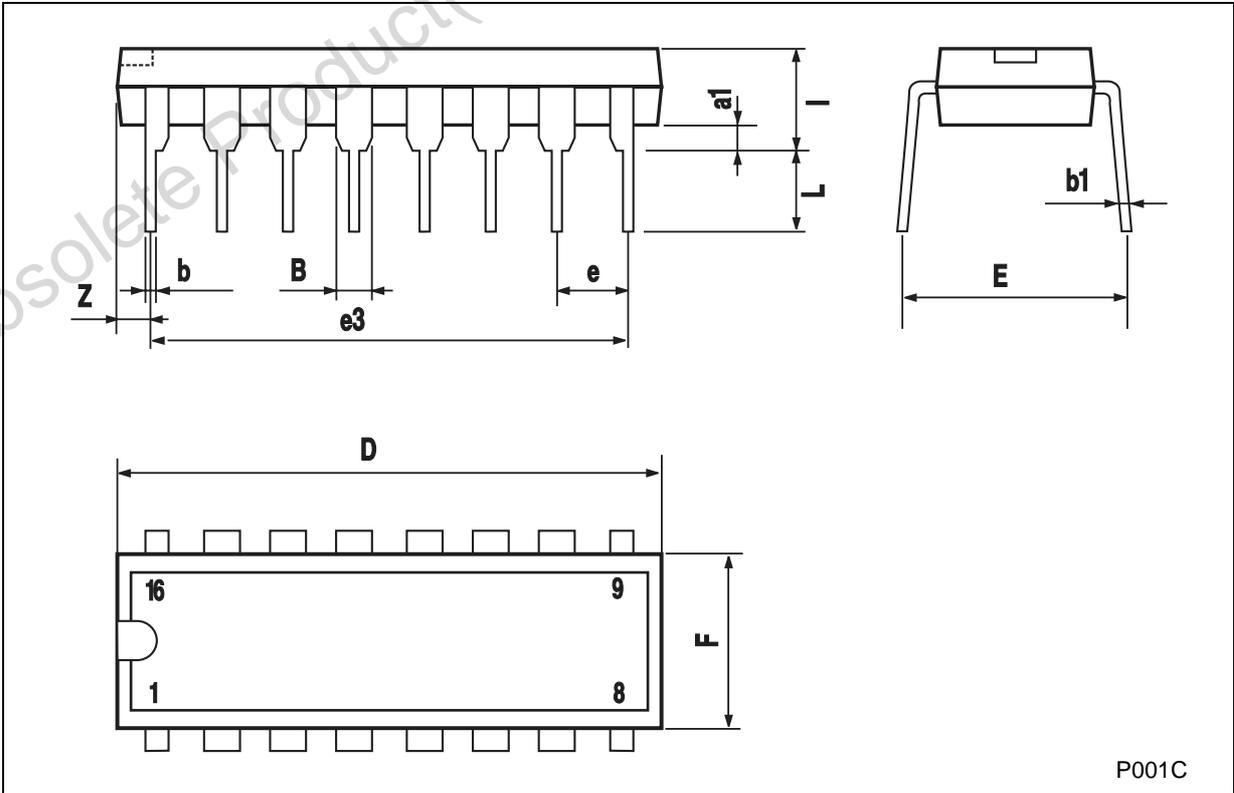
TEST	SWITCH
t <sub>PLH</sub> , t <sub>PHL</sub>	Open
t <sub>PZL</sub> , t <sub>PLZ</sub>	V <sub>CC</sub>
t <sub>PZH</sub> , t <sub>PHZ</sub>	GND

C<sub>L</sub> = 50pF/150pF or equivalent (includes jig and probe capacitance)  
 R<sub>1</sub> = 1KΩ or equivalent  
 R<sub>T</sub> = Z<sub>OUT</sub> of pulse generator (typically 50Ω)

**WAVEFORM 1 : PROPAGATION DELAY TIMES** ( $f=1\text{MHz}$ ; 50% duty cycle)**WAVEFORM 2 : OUTPUT ENABLE AND DISABLE TIMES** ( $f=1\text{MHz}$ ; 50% duty cycle)

**Plastic DIP-16 (0.25) MECHANICAL DATA**

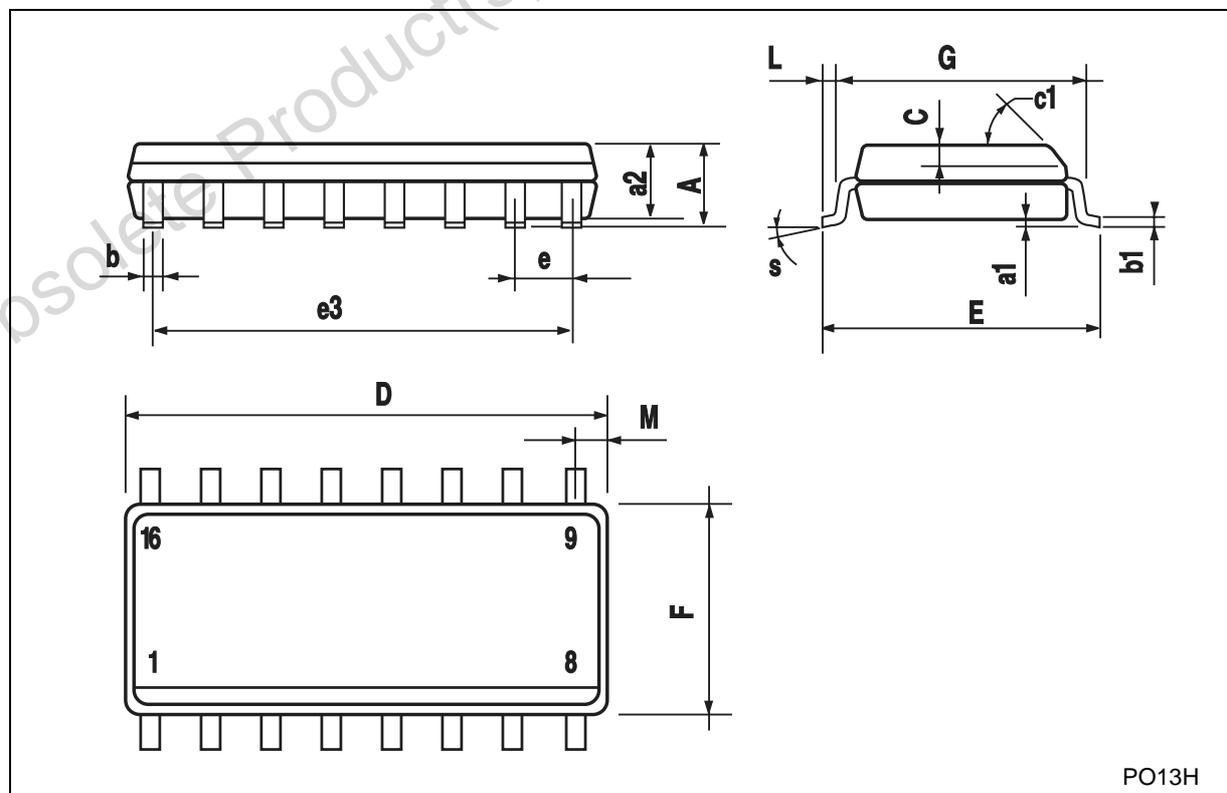
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
B	0.77		1.65	0.030		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
E		8.5			0.335	
e		2.54			0.100	
e3		17.78			0.700	
F			7.1			0.280
I			5.1			0.201
L		3.3			0.130	
Z			1.27			0.050



P001C

## SO-16 MECHANICAL DATA

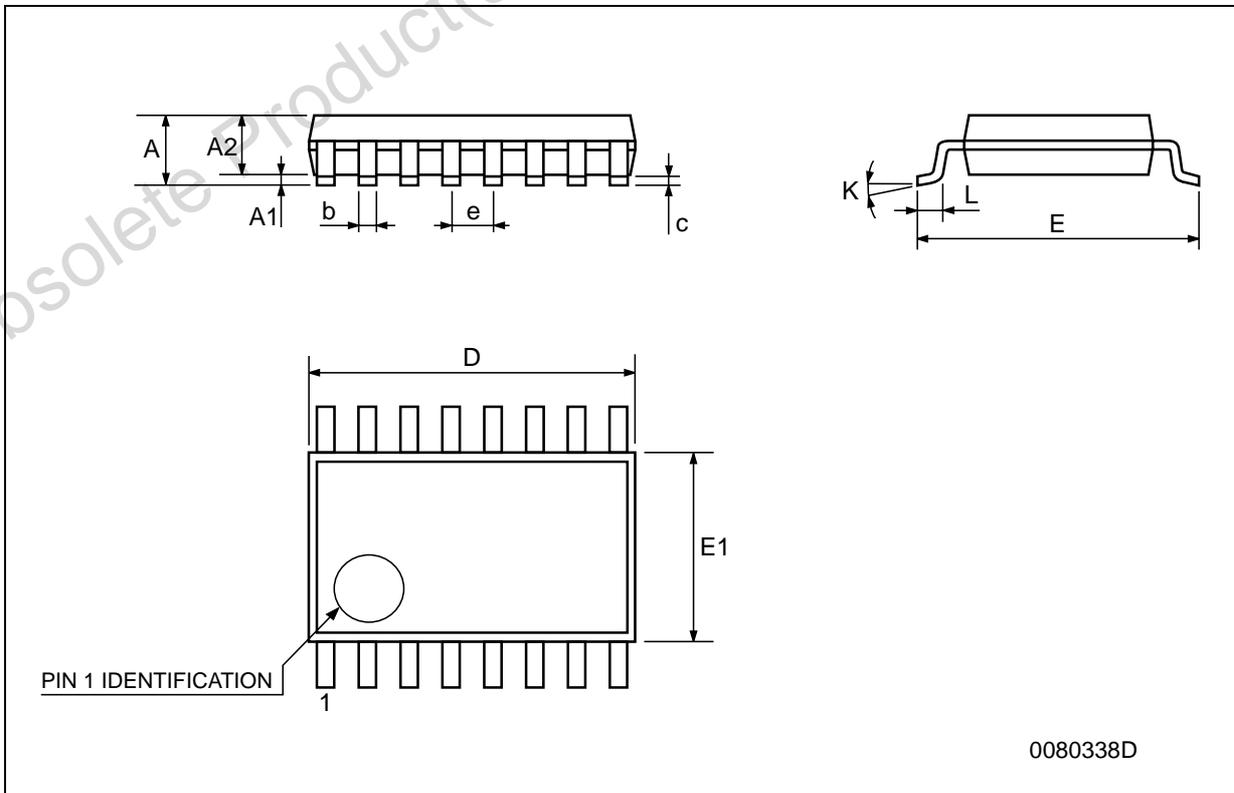
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			1.75			0.068
a1	0.1		0.2	0.003		0.007
a2			1.65			0.064
b	0.35		0.46	0.013		0.018
b1	0.19		0.25	0.007		0.010
C		0.5			0.019	
c1	45° (typ.)					
D	9.8		10	0.385		0.393
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		8.89			0.350	
F	3.8		4.0	0.149		0.157
G	4.6		5.3	0.181		0.208
L	0.5		1.27	0.019		0.050
M			0.62			0.024
S	8° (max.)					



PO13H

**TSSOP16 MECHANICAL DATA**

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			1.2			0.047
A1	0.05		0.15	0.002	0.004	0.006
A2	0.8	1	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.0089
D	4.9	5	5.1	0.193	0.197	0.201
E	6.2	6.4	6.6	0.244	0.252	0.260
E1	4.3	4.4	4.48	0.169	0.173	0.176
e		0.65 BSC			0.0256 BSC	
K	0°		8°	0°		8°
L	0.45	0.60	0.75	0.018	0.024	0.030



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